

Seat No.: _____

Enrolment No. _____

GUJARAT TECHNOLOGICAL UNIVERSITY

BE - SEMESTER-VIII (NEW) - EXAMINATION – SUMMER 2018

Subject Code: 2182008

Date: 30/04/2018

Subject Name: MEMS and Nanotechnology (Departmental Elective - III)

Time: 10:30 AM to 01:00 PM

Total Marks: 70

Instructions:

1. Attempt all questions.
2. Make suitable assumptions wherever necessary.
3. Figures to the right indicate full marks.
4. Figures to the right indicate full marks.

| | MARKS |
|--|-----------|
| Q.1 (a) Give at least three distinct advantages of miniaturization of machines and device. | 03 |
| (b) Give the comparison between Microelectronics and Microsystems. | 04 |
| (c) Describe the various domain applications of MEMS devices. | 07 |
| Q.2 (a) What are the principal application of microsensors, actuators and fluidics? | 03 |
| (b) Evaluate the effect of creep in MEMS devices diminishes at higher values of temperature. | 04 |
| (c) Estimate the damping coefficient in a force balanced micro accelerometer, as illustrated in Fig. 1, for air and for silicone oil as the damping fluid. Assume that the micro accelerometer operates at 20°C. | 07 |

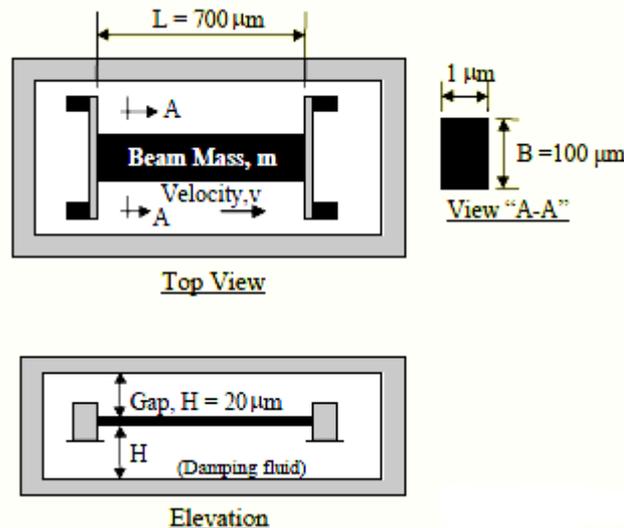
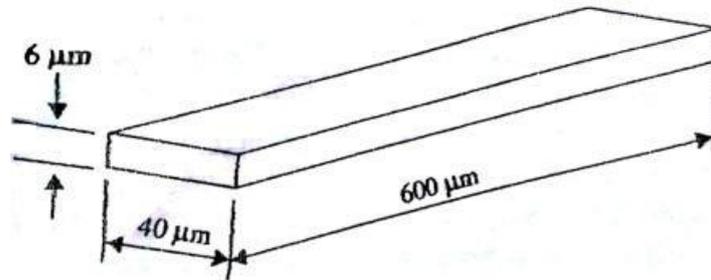


Fig. 1

OR

- (c) Determine the shift of natural frequency of a fixed-end beam made of silicon, with geometry and dimensions shown below when subjected to a longitudinal stress at 187 MPa. The dimensions of the beam are width $b = 40 \times 10^{-6} \text{ m}$, depth (thickness) $h = 6 \times 10^{-6} \text{ m}$, length $L = 600 \times 10^{-6} \text{ m}$. The following properties are applicable to silicon beam:



Young's modulus $E = 190,000 \text{ MPa}$
 Mass density $\rho = 2300 \text{ kg/m}^3$

- Q.3** (a) Differentiate between Ion Implantation and Diffusion process. **03**
 (b) Explain the working and applications of different types of Micro accelerometers. **04**
 (c) Explain the Czochralski method for producing single-crystal silicon. **07**

OR

- Q.3** (a) Differentiate between Squeeze film and damping in shear. **03**
 (b) Discuss the tools available for characterizing nanostructures. **04**
 (c) Explain the Photolithography process in detail with a suitable example. **07**

- Q.4** (a) What is etching? Give the types of it. **03**
 (b) Explain Chemical Vapor Deposition process. **04**
 (c) Determine the required electric voltage for ejecting a droplet of ink from an inkjet printer head (shown in below figure) using PZT piezoelectric crystal as a pumping mechanism. The ejected ink will have a resolution of 300 dpi (dots per inch). The ink droplet is assumed to produce a dot with a film thickness of $1 \mu\text{m}$ on the paper. The geometry and dimension of the printer head is illustrated below. Assume that the ink droplet takes a shape of a sphere and the inkwell is always re-filled after ejection. **07**

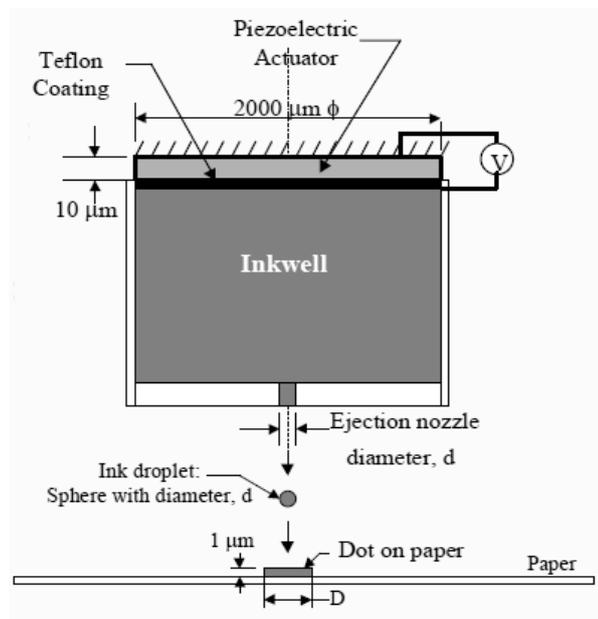


Fig .2

OR

- Q.4** (a) Explain working principle of Chemical Vapor Deposition process. **03**
(b) Discuss the major technical issues to be handled in BIOMEMS products. **04**
(c) Explain scaling in fluid mechanics. **07**
- Q.5** (a) Differentiate between SEM and TEM. **03**
(b) What are the types and possible applications of carbon nanotubes? **04**
(c) “At the nanoscale, the job of "seeing" is done by molecular recognition.” Explain. **07**

OR

- Q.5** (a) Explain the use of carbon nanotubes as nano bio sensors. **03**
(b) Justify: At the nanometer scale, properties become size dependent. **04**
(c) Explain the role of Finite Element Analysis in the Design of MEMS structures. **07**
